



SLOVENSKI STANDARD SIST EN IEC 62878-1:2021

01-junij-2021

**Tehnologija sestavov z vdelenimi elementi - 1. del: Osnovna specifikacija za
substrate z vdelenimi elementi**

Device embedding assembly technology - Part 1: Generic specification for device
embedded substrates

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Ta slovenski standard je istoveten z: EN IEC 62878-1:2019
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ICS:

31.180	Tiskana vezja (TIV) in tiskane plošče	Printed circuits and boards
31.190	Sestavljeni elektronski elementi	Electronic component assemblies

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EUROPEAN STANDARD
NORME EUROPÉENNE
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EN IEC 62878-1

December 2019

ICS 31.180; 31.190

English Version

**Device embedding assembly technology - Part 1: Generic
specification for device embedded substrates
(IEC 62878-1:2019)**

Techniques d'assemblage avec appareil(s) intégré(s) -
Partie 1: Spécification générique pour substrats avec
appareil(s) intégré(s)
(IEC 62878-1:2019)

Montageverfahren für eingebettete Bauteile - Teil 1:
Fachgrundspezifikation für Trägermaterial mit eingebetteten
Bauteilen
(IEC 62878-1:2019)

This European Standard was approved by CENELEC on 2019-11-18. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the CEN-CENELEC Management Centre has the same status as the official versions.

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

EN IEC 62878-1:2019 (E)**European foreword**

The text of document 91/1597/FDIS, future edition 1 of IEC 62878-1, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62878-1:2019.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2020-08-18
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2022-11-18

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The text of the International Standard IEC 62878-1:2019 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60068-1:2013	NOTE	Harmonized as EN 60068-1:2014 (not modified)
IEC 60068-2-45	NOTE	Harmonized as EN 60068-2-45
IEC 60068-2-58	NOTE	Harmonized as EN 60068-2-58
IEC/TR 61340-5-2	NOTE	Harmonized as CLC/TR 61340-5-2
IEC 62421	NOTE	Harmonized as EN 62421

Annex ZA

(normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60068-2-1	-	Environmental testing - Part 2-1: Tests - Test A: Cold	EN 60068-2-1	-
IEC 60068-2-2	-	Environmental testing - Part 2-2: Tests - Test B: Dry heat	EN 60068-2-2	-
IEC 60068-2-6	-	Environmental testing - Part 2-6: Tests - Test Fc: Vibration (sinusoidal)	EN 60068-2-6	-
IEC 60068-2-14	-	Environmental testing - Part 2-14: Tests - Test N: Change of temperature	EN 60068-2-14	-
IEC 60068-2-21	-	Environmental testing - Part 2-21: Tests - Test U: Robustness of terminations and integral mounting devices	EN 60068-2-21	-
IEC 60068-2-27	-	Environmental testing - Part 2-27: Tests - Test Ea and guidance: Shock	EN 60068-2-27	-
IEC 60068-2-69	-	Environmental testing – Part 2-69: Tests – Test Te/Tc: Solderability testing of electronic components and printed boards by the wetting balance (force measurement) method	EN 60068-2-69	-
IEC 60068-2-78	-	Environmental testing - Part 2-78: Tests - Test Cab: Damp heat, steady state	EN 60068-2-78	-
IEC 60194-2	-	Printed boards design, manufacture and assembly - Vocabulary - Part 2: Common usage in electronic technologies as well as printed board and electronic assembly technologies	-	-
IEC 61340-5-1	-	Electrostatics - Part 5-1: Protection of electronic devices from electrostatic phenomena - General requirements	EN 61340-5-1	-

EN IEC 62878-1:2019 (E)

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61340-5-3	-	Electrostatics - Part 5-3: Protection of electronic devices from electrostatic phenomena - Properties and requirements classification for packaging intended for electrostatic discharge sensitive devices	EN 61340-5-3	-
IEC 61760-4	-	Surface mounting technology - Part 4: Classification, packaging, labelling and handling of moisture sensitive devices	EN 61760-4	-
IEC 62137-1-4	-	Surface mounting technology - Environmental and endurance test methods for surface mount solder joint - Part 1-4: Cyclic bending test	EN 62137-1-4	-
IEC 62878-1-1	-	Device embedded substrate - Part 1-1: Generic specification - Test methods	EN 62878-1-1	-
IEC/TR 62878-2-2	-	Device embedded substrate - Part 2-2: Guidelines - Electrical testing	-	-
IEC/TS 62878-2-1	-	Device embedded substrate - Part 2-1: Guidelines - General description of technology	-	-
IEC/TS 62878-2-3	-	Device embedded substrate - Part 2-3: Guidelines - Design guide	-	-
IEC/TS 62878-2-4	-	Device embedded substrate - Part 2-4: Guidelines - Test element groups (TEG)	-	-
J-STD 033	-	Handling, Packing, Shipping, and Use of Moisture/Reflow and/or Process Sensitive Components	-	-

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**Device embedding assembly technology –
Part 1: Generic specification for device embedded substrates**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

DEVICE EMBEDDING ASSEMBLY TECHNOLOGY –

Part 1: Generic specification for device embedded substrates

FOREWORD

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International Standard IEC 62878-1 has been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
91/1597/FDIS	91/1616/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62878 series, published under the general title *Device embedded substrate*, can be found on the IEC website.

Future standards in this series will carry the new general title as cited above. Titles of existing standards in this series will be updated at the time of the next edition.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

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